CALL FOR PAPERS

The Leading International Components, Packaging, and Manufacturing Technology Symposium

IEEE CPMT Symposium Japan 2019

November 18 – 20, 2019,
Kyoto Univ. Clock Tower Centennial Hall, Kyoto, JAPAN
https://www.ieee-csj.org/

"Electronics Packaging for AI and Beyond"

"IEEE CPMT Symposium Japan (ICSJ)" is one of the most widely recognized international conferences sponsored by the **IEEE EPS** and has been held annually in Kyoto in November. The conference originally started in 1992 as "The VLSI Packaging Workshop in Japan" and was re-named to "ICSJ" in 2010. ICSJ will provide a platform for you to communicate and interact with global leaders in packaging technology.

Electronics Packaging for AI and Beyond: Over the last several decades, the continuous development of semiconductor chips has supported the growth of computing performance. Computer systems have begun to enrich our lives, and now with the emergence of artificial intelligence (AI) systems, these systems will evolve to be even more intertwined with our lives. Our focus has now shifted to how we realize, oversee, and cooperate with the AI. At past ICSJ conferences, our focus had evolved alongside these emerging technologies where we had discussed and tried to predict the future state of the electronics packaging technologies which would lead to new computer applications. In 2019, the conference's theme will be the contribution of electronics packaging to *AI and beyond*, and will emphasize the following main topics: **Photonics, Advanced Packaging, Power & Automotive Electronics, Bioelectronics,** and **Thermal Management**. Additional topics of primary interest to the participants are listed below.

Other topics include (but not limited to):

+ 3D Packaging & Chip-on-Chip
+ Advanced Fine Pitch Packaging, Micro Bumping, Wafer Level CSP
+ Board-Level Integration & Integrated Substrate
+ Laminated Materials & Processing, Materials for Packaging
+ Reliability & Failure Mechanisms
+ Packaging for High-Speed Electrical Interconnect
+ Signal Integrity / Power Integrity
+ RF Components & Modules
+ Additive Manufacturing, 3D Printed Electronics
+ Brain-like Neuromorphic Chip Assembly
+ Resilient Packaging for Autonomous System
+ Low Power / Low Temperature / Ultra Low Noise System Packaging

Bring your latest research results, and share and discuss your worth with experts from industry and academia. Anybody in the field of the packaging technologies is very welcome to present their latest accomplishments and participate in the discussion. The conference will provide a perfect opportunity to communicate, interact, and exchange technical ideas. Young researchers with less than 2 years' experience in their professions and all students including Ph.D. are also welcome to the poster session called the "Early Career Researchers' (ECR)" session, which serves as an introduction to technical presentations and fruitful communications with experts. Authors are invited to submit an abstract through our website, https://www.ieee-csj.org. **The abstract deadline is May 24, 2019**. Acceptance notifications will be sent by July 5, 2019. Accepted authors are requested to submit their manuscript by September 6, 2019 for the Technical Digest, which will be available via **IEEE Xplore**. A 4-page manuscript is required for the regular session, while a 2-page manuscript is enough for ECR session.

Plenary & Special Speakers

Plenary Speakers

Hideo Hosono	(Tokyo Institute of Technology)
Peter O'Brien	(Tyndall National Institute)
Sebastian Volz	(École Centrale Paris)

EPS Special Session Speakers

Chris Bailey	(University of Greenwich)
Beth Keser	(Intel Corporation)

Session Invited Speakers

Tanja Braun	(Fraunhofer IZM)
Richard Pitwon	(Resolute Photonics Ltd.)
Lars Brusberg	(Corning Research & Development Corporation)
Bernard HL Lee	(SENKO Advanced Components (HK) Ltd)
Tolga Tekin	(Fraunhofer IZM)
Christian Koos	(Karlsruhe Institute of Technology)
Chih-Ming Wang	(National Dong Hwa University)

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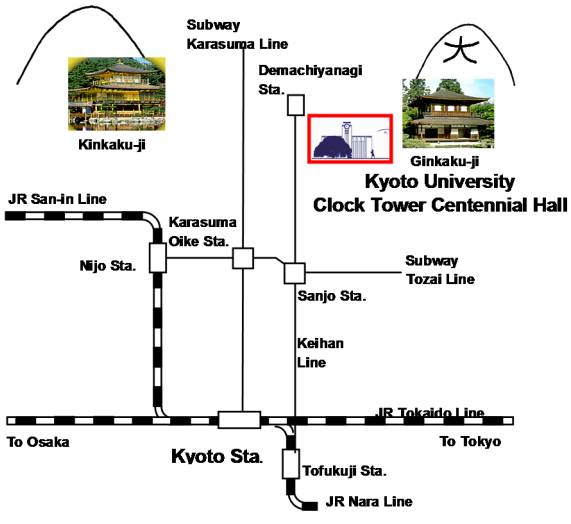
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